



IPC-TM-650 TEST METHODS MANUAL

1 Scope This test method is to determine the moisture and insulation resistances of applied polymer solder mask under two separate prescribed conditions of temperature and humidity. One is for Class T and the other Class H. Raw material qualification testing is performed on designated comb patterns. Production quality conformance testing is performed on a standard "Y" pattern.

2 Applicable Documents

IPC-SM-840 Qualification and Performance of Permanent Solder Mask

J-STD-004 Requirements for Soldering Fluxes

IPC-A-600 Acceptability for Printed Boards

3 Test Specimens

3.1 Qualification Testing

3.1.1 Class H Three IPC-B-25A boards using the D comb patterns with 0.318 mm [12.50 mil] lines/spaces (see Figure 1). Of which, two is to be coated and one uncoated with solder mask according to the solder mask supplier's recommendations.

3.1.2 Class T Three IPC-B-25A boards using the E and F comb patterns with 0.406 mm [16.00 mil] lines and 0.508 mm [20.00 mil] spaces (see Figure 1). Of which, two are to be coated and one uncoated with solder mask according to the solder mask supplier's recommendations.

3.2 Conformance Testing IPC-B-25A board C ("Y" shape) pattern with 0.635 mm lines/0.635 mm spacing [25.00 mil lines/25.00 mil spacing] or minimum spacing on the production board (See Figure 1), whichever is smaller, coated with solder mask according to the solder mask suppliers recommendations.

4 Apparatus

4.1 Chamber A clean chamber capable of programming and recording an environment of $25 \pm 2^\circ\text{C}$ [$77^\circ \pm 3.6^\circ\text{F}$] to at least $65 \pm 2^\circ\text{C}$ [$149^\circ \pm 3.6^\circ\text{F}$] and 90-98% relative humidity.

Number 2.6.3.1 (Supersedes 2.6.3.1C for Solder Mask Test)	
Subject Moisture and Insulation Resistance - Solder Mask	
Date 07/00	Revision D
Originating Task Group Solder Mask Performance Task Group (5-33b)	

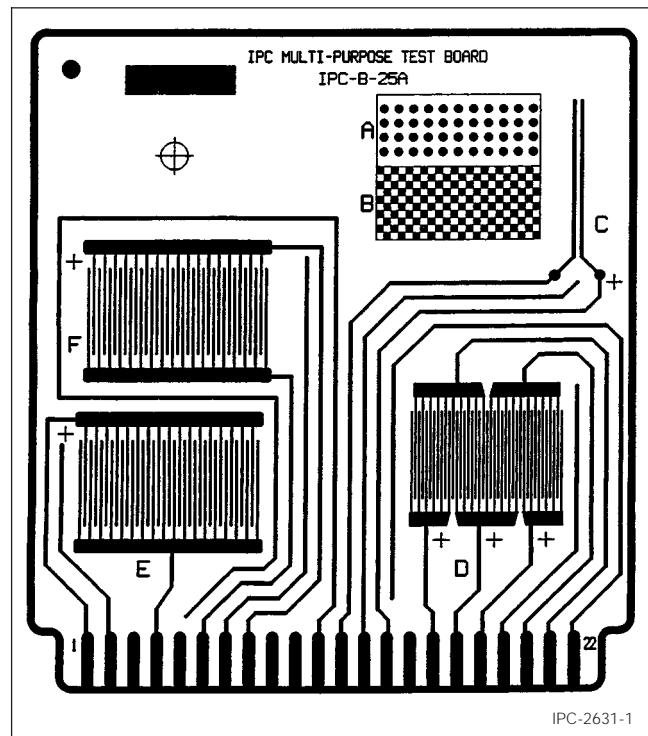


Figure 1 IPC-B-25A Test Board

4.2 Power Supply Capable of producing a standing bias potential of 100 VDC with a tolerance of $\pm 10\%$.

4.3 Resistance Meter Capable of reading high resistance (10^{12} ohms or greater), with a test voltage of 100 VDC.

4.4 Oven Capable of maintaining at least 120°C [248°F].

4.5 Timer

4.6 Solder Pot

4.7 Tongs

4.8 Soldering Iron

4.9 Flux Water white rosin (R or RMA) with halide content less than 0.5%, i.e., type Symbol A and B or ROL0 and ROL1 according to J-STD-004.

IPC-TM-650		
Number 2.6.3.1	Subject Moisture and Insulation Resistance - Solder Mask	Date 07/00
Revision D		

5 Test

5.1 Ambient Conditions Class T and Class H: 25°, +2°, -5°C [77°, +3.6°, -9°F] and 40-50% relative humidity.

5.2 Test Conditions

5.2.1 Class T 65° ± 2°C [149° ± 3.6°F], with 90 ± 3% relative humidity, no bias, static, 24 hours.

5.2.2 Class H 25° to 65° ± 2°C [77 to 149° ± 3.6°F], with 90, -5, +3% relative humidity, 50 VDC bias, cycling, 6²/₃ days.

5.3 Specimen Preparation (Both Classes)

5.3.1 Positive, permanent and noncontaminating identification of the test specimens is of paramount importance.

5.3.2 Visually inspect the test specimens for any obvious defects, as described in the IPC-A-600. If there is any doubt about the overall quality of any test specimen, the test specimen should be discarded.

5.3.3 One uncoated specimen subjected to the same processing (except solder mask coating) as the coated specimens shall be supplied with each set of coated samples for testing as a control.

5.3.4 Subject one of the IPC-B-25A boards which has been coated with solder mask to solder in accordance with J-STD-004. Clean the residual flux from the boards surface. First rinse with deionized or distilled water (30 seconds minimum), followed by immersing the board in 2-propanol and agitate (30 seconds maximum). While the board is immersed, gently scrub the surface with a soft bristle brush. Then spray the board with clean 2-propanol.

5.3.5 Bake in an oven maintained at 50°C [122°F] for three hours minimum.

5.4 Electrical Connections (Both Classes)

5.4.1 For qualification specimens, solder a single strand PTFE insulated wire or equivalent to each pad of the appropriate comb pattern as specified in 3.1. These wires will be used to connect each pad of the designated comb pattern to polarization and insulation resistance testing. When soldering the wires onto the pads care should be taken to ensure that the flux does not splatter onto the combs. A simple off-

contact shield fixture should be used to protect the test patterns from flux spitting during soldering.

Note: An alternate method is to use gold plated alligator clips.

5.4.2 For quality conformance specimens, solder single strand PTFE insulated wire or equivalent to each pad of the connection points of the C pattern. These wires will be used to connect the C pattern to polarization and insulation resistance testing.

5.5 Soldering Flux The flux shall not be removed.

Note: If the flux has contaminated the pattern on the control, the sample shall be discarded and a new one used. It cannot be cleaned because it will not represent the cleaning process that was used prior to solder mask application.

5.6 Specimen Handling For the remainder of the test, the surface of the test specimens either uncoated or coated with solder mask should not be handled or exposed to any other contaminating influence.

5.7 Class H Procedures

5.7.1 Class H Testing

5.7.1.1 Condition the specimens at 50 ± 2°C [122 ± 3.6°C] with no added humidity, for a period of 24 hours.

5.7.1.2 Allow the specimens to cool, measure and record the initial insulation resistance measurements at ambient laboratory conditions. Apply 100 VDC on the specimen's test points as specified in 3.1.1 or 3.2 with the resistance meter and take the reading after one minute. See note 6.2.

5.7.1.3 Place specimens in a chamber, in a vertical position and under a condensation drip shield. Connect the 50 VDC voltage source to the specimen's test points as indicated in 3.1.1 or 3.2. Each chamber load shall contain at least one uncoated board that is representative of the cleaning process used prior to solder mask application for each solder mask tested.

5.7.1.4 The test points for qualification tests are 1 to 2, 3 to 2, 3 to 4 and 5 to 4 on the D comb pattern. On the D comb pattern, test points 1, 3 and 5 are connected to the positive terminal and test points 2 and 4 are connected to the negative terminal of the resistance meter. For quality conformance, the pair of test points is 1 to 2 on the C pattern. One side of

IPC-TM-650		
Number 2.6.3.1	Subject Moisture and Insulation Resistance - Solder Mask	Date 07/00
Revision D		

the C pattern should be connected to the negative terminal and the other side to the positive.

5.7.1.5 Close chamber door and apply a 50 volt bias to all comb patterns (D or C patterns) tested.

5.7.1.6 Expose test specimens to 20 cycles of temperature and humidity (see Figure 2). Polarizing voltage shall be maintained throughout the entire 20-cycle period. Humidity shall be maintained at 85% minimum through the cycles except that when going to low temperature in Step c below, the humidity may drop to 80% minimum.

One cycle is as follows:

a. Start test at 25°C [77°F] and raise the temperature to 65°C [149°F] over a time span of 1.75 ± 0.75 hours

b. Maintain temperature at 65°C [149°F] for 3, +0.5, -0 hours
c. Lower the temperature from 65°C [149°F] to 25°C [77°F] over 1.75 ± 0.5 hours

Note: There shall be no delay between cycles.

5.7.2 Class H Measurement

5.7.2.1 Disconnect 50 VDC polarizing voltage source before taking the insulation resistance measurements. Insulation resistance shall be read as specified in 5.7.1.4. Electrical connections to specimens shall be made so that electrical polarization voltage and the test voltage, of the same polarity are connected to the same terminal.

5.7.2.2 For qualification testing, measure and record resistance once every 24 hours (if required - see 5.7.3.1), between

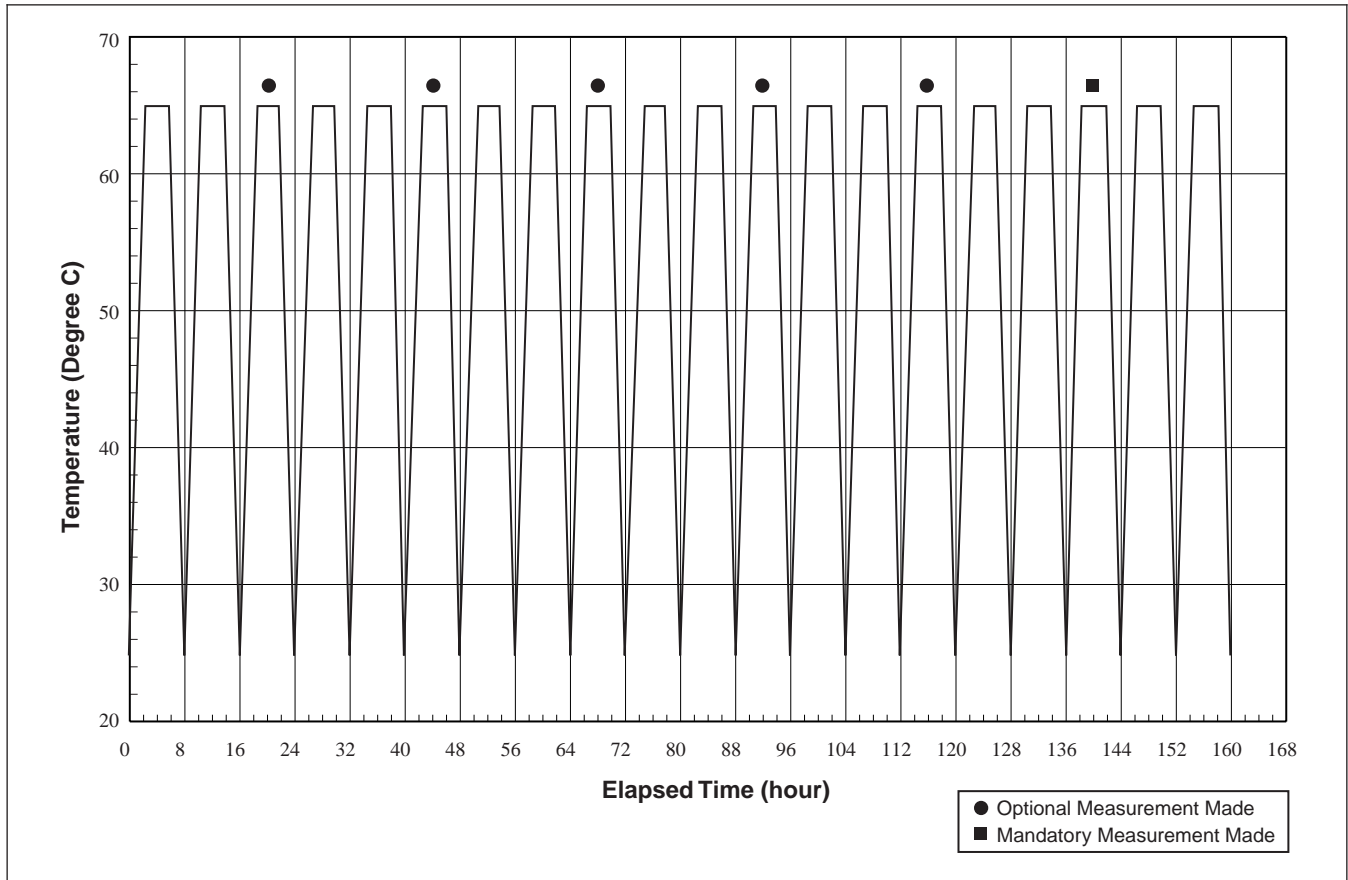


Figure 2 Moisture and Insulation Resistance Test Graph

IPC-TM-650		
Number 2.6.3.1	Subject Moisture and Insulation Resistance - Solder Mask	Date 07/00
Revision D		

the 2nd and 3rd hour of the high phase of each cycle. These measurements are to be conducted without opening the chamber. Completion of qualification testing shall be accomplished by disconnecting the bias voltage; remove the specimens from the chamber, read and record insulation resistance after one hour and before two hours at ambient laboratory conditions.

5.7.2.3 For conformance testing with the C pattern, the measurements must be taken after disconnecting the bias voltage, removal of the specimens from the chamber and after one hour and before two hours stabilization at ambient laboratory conditions. See note 6.2.

5.7.3 Class H Evaluation

5.7.3.1 Each test specimen shall be evaluated for insulation resistance quality following and/or during the stated conditions. Although several insulation resistance readings may be taken during the test, only the final (18th cycle) readings in high temperature phase in the chamber and the reading taken outside the chamber shall be used to determine pass/fail criteria. **Other readings are optional and may be used for diagnostic information or aborting the test.**

5.7.3.2 After completion of all electrical testing, the test specimens shall be examined for mealing, blisters, delamination or other forms of degradation following the 24-hour stabilization at ambient laboratory conditions. See note 6.2.

5.8 Class T Procedures

5.8.1 Class T Testing

5.8.1.1 Condition the specimens at $50 \pm 2^\circ\text{C}$ [$122 \pm 3.6^\circ\text{C}$] with no added humidity, for a period of 24 hours.

5.8.1.2 Remove the specimens from the oven and cool to laboratory ambient temperature. Apply 100 VDC on the specimen's pair of test points on comb patterns E and F. See note 6.2.

5.8.1.3 Test points for qualification are at each pair of terminals on the E and F comb patterns. One of the test points is connected to the negative terminal and the other to the positive terminal. For quality conformance, the pair of test points is 1 to 2 on the C pattern. One side of the C pattern should be connected to the negative terminal and the other side to the positive.

5.8.1.4 Place the specimens in the test chamber in the vertical position under a condensation drip shield.

5.8.1.5 Each chamber load shall contain at least one uncoated board that is representative of the cleaning process used prior to solder mask application for each solder mask tested.

5.8.1.6 Close the chamber door and bring the chamber to 65°C [149°F] and 90% relative humidity.

5.8.1.7 Allow specimens to stabilize at test conditions for 24 hours.

5.8.2 Class T Measurement

5.8.2.1 Connect the resistance meter to the appropriate test points. For qualification testing, one of the test points of the two terminal E and F patterns are connected to the negative terminal and the other test point to the positive. For quality conformance testing, one side of the C pattern ("Y" pattern) should be connected to the negative terminal and the other side to the positive.

5.8.2.2 Apply 100 VDC on the specimens test points with the resistance meter and take the reading after one minute with the patterns under test conditions.

5.8.3 Class T Evaluation

5.8.3.1 Three separate sets of measurements are to be recorded for the uncoated specimen, the 'as received' specimen, and the specimen after solder exposure. Each set of readings shall be averaged and shall be greater than the minimum listed in the relevant specification. No individual insulation resistance value may be less than $0.1 \times IR_{\min}$. Two measurements may be excluded from calculating the average if there is an assignable cause of low insulation resistance that can be attributable to the laminate itself or to the process used to produce the board. Such assignable causes include:

- Contamination of the insulating surface of the board such as lint, solder splints, or water droplets from the conditioning chamber.
- Incompletely etched patterns that decrease the insulating space between conductors by more than the amount allowed in the appropriate design requirements drawing.
- Scratched, cracked or obviously damaged insulation between conductors.

IPC-TM-650		
Number 2.6.3.1	Subject Moisture and Insulation Resistance - Solder Mask	Date 07/00
Revision D		

5.8.1.1 The average insulation resistance (IR_{avg}) is calculated from:

$$IR_{avg} = 10 \left[\frac{1}{N} \sum_{i=1}^N \log IR_i \right]$$

Where:

N = Number of test points (12 nominal)

IR_i = Individual insulation resistance measurements.

5.8.1.2 After completion of all electrical testing, the test specimens shall be examined for mealing, blisters, delamination or other forms of degradation following 24-hour stabilization at laboratory ambient temperatures.

6 Notes

6.1 Initial wire placement must be maintained to ensure reproducible results.

6.2 Specimens may be stabilized at ambient conditions specified, inside the chamber.